

## AMENDMENTS TO THE CLAIMS

Sub 5. 1. (Currently Amended) A suspension bonding pad ~~for electrically bonding to electrically~~  
bond a magnetic head terminal comprising a metal pad having a bonding substance applied as a  
surface finishing material, the surface finishing material being heat treated prior to bonding to a  
surface.

2. (Currently Amended) A suspension bonding pad ~~for electrically bonding to electrically~~  
bond a magnetic head terminal as set forth in claim 1, wherein said bonding substance is solder.

3. (Currently Amended) A suspension bonding pad ~~for electrically bonding to electrically~~  
bond a magnetic head terminal as set forth in claim 1, wherein said bonding substance is a  
conductive polymer.

4. (Currently Amended) A suspension bonding pad ~~for electrically bonding to electrically~~  
bond a magnetic head terminal as set forth in claim 1, wherein said bonding substance is an  
adhesive.

5. (Currently Amended) A suspension bonding pad ~~for electrically bonding to electrically~~  
bond a magnetic head terminal as set forth in claim 1, wherein said bonding substance is a film.

6. (Currently Amended) A suspension bonding pad ~~for electrically bonding to electrically~~  
bond a magnetic head terminal as set forth in claim 2, wherein a bump height for the solder is  
approximately 50-300  $\mu\text{m}$ , and a bump diameter for the solder is less than 180  $\mu\text{m}$ .

7. (Currently Amended) A disk drive suspension comprising:  
a bonding pad for electrically bonding a magnetic head terminal, wherein said bonding  
pad includes a metal pad having a bonding substance applied as a surface finishing material, the  
surface finishing material being heat treated prior to bonding to a surface.

8. (Currently Amended) The disk drive suspension as ~~claim~~ set forth in claim 7, wherein  
said bonding substance is solder.

9. (Currently Amended) The disk drive suspension as ~~claim~~ set forth in claim 7, wherein  
said bonding substance is a conductive polymer.

10. (Currently Amended) The disk drive suspension as ~~claim~~ set forth in claim 7, wherein  
said bonding substance is an adhesive.

11. (Currently Amended) The disk drive suspension as ~~claim~~ set forth in claim 7, wherein  
said bonding substance is a film.

12. (Currently Amended) The disk drive suspension as ~~claim~~ set forth in claim 8, wherein a bump height for the solder is approximately 50-300  $\mu\text{m}$ , and a bump diameter for the solder is less than 180  $\mu\text{m}$ .

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